

Features

- Halogen Free. "Green" Device (Note 1)
- Epoxy Meets UL 94 V-0 Flammability Rating
- Lead Free Finish/RoHS Compliant ("P" Suffix Designates RoHS Compliant. See Ordering Information)

Maximum Ratings @ 25°C Unless Otherwise Specified

- Operating Junction Temperature Range: -55°C to +150°C
- StorageTemperature Range: -55°C to +150°C
- Thermal Resistance: 250°C/W Junction to Ambient (Note1)

| Parameter | Symbol | Rating | Unit |
|---|------------------|-------------------------|------|
| Collector-Base Voltage | V _{CBO} | 100 | V |
| Collector-Emitter Voltage | V _{CEO} | 80 | V |
| Emitter-Base Voltage | V _{EBO} | 5 | V |
| Collector Current | Ι _C | 1.0 | А |
| Base Current | I _B | 0.1 | А |
| Peak Base Current (t _p <1ms) | I _{BM} | 0.2 | А |
| | | 0.50 ^(Note2) | |
| Collector Power Dissipation | Pc | 0.95 ^(Note3) | W |
| | | 1.35 ^(Note4) | |

Classification Of h_{FE(1)}

| Rank | BCX56 | BCX56-10 | BCX56-16 |
|-----------------------------|--------|----------|----------|
| Range of h _{FE(1)} | 63-250 | 63-160 | 100-250 |
| Marking | BH | BK | BL |

Note: 1. Halogen free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

Note:2. Device mounted on an FR4 PCB, Single-sided copper, tin-plated and standard footprint.

Note:3. Device mounted on an FR4 PCB, Single-sided copper, mounting pad for collector 1cm²

Note:4.Device mounted on an FR4 PCB, Single-sided copper, mounting pad for collector 6cm²

Pin Configuration - Top View

Internal Structure









Suggested Solder Pad Layout

0.38

0.35

1.40

0.53

0.44

1.60

1.50

TYP.

н

J

Κ

L

0.015 0.021

0.014 0.017

0.055 0.063

0.059





Electrical Characteristics @ 25°C Unless Otherwise Specified

| Parameter | Symbol | Min | Тур | Мах | Units | Conditions |
|--------------------------------------|----------------------|-----|-----|-----|-------|---|
| Collector-Base Breakdown Voltage | V _{(BR)CBO} | 100 | | | V | I _C =100μA, I _E =0 |
| Collector-Emitter Breakdown Voltage | V _{(BR)CEO} | 80 | | | V | I _C =10mA, I _B =0 |
| Emitter-Base Breakdown Voltage | V _{(BR)EBO} | 5 | | | V | I _E =10μA, I _C =0 |
| Collector-Base Cutoff Current | I _{CBO} | | | 0.1 | μA | $V_{CB}=30V, I_{E}=0$ |
| Emitter-Base Cutoff Current | I _{EBO} | | | 0.1 | μA | V _{EB} =5.0V, I _C =0 |
| DC Current Gain | h _{FE(1)} | 63 | | 250 | | V _{CE} =2.0V, I _C =150mA |
| | h _{FE(2)} | 40 | | | | V _{CE} =2.0V, I _C =5mA |
| | h _{FE(3)} | 25 | | | | V _{CE} =2.0V, I _C =500mA |
| Collector-Emitter Saturation Voltage | V _{CE(sat)} | | | 0.5 | V | I _C =500mA, I _B =50mA |
| Base-Emitter Voltage | V _{BE} | | | 1.0 | V | V _{CE} =2.0V, I _C =500mA |
| Transition Frequency | f _T | | 130 | | MHz | V _{CE} =5.0V, I _C =10mA, f=100MHz |



BCX56/BCX56-10/BCX56-16

Curve Characteristics





Attention

1, Any and all Huban products described or contained herein do not have specifications that can handle applications that require extremely high levels of reliability, such as life support systems, aircraft's control systems, or other applications whose failure can be reasonably expected to result in serious physical and /or material damage. Consult with your Huban representative nearest you before using any Huban products described or contained herein in such applications.

2,Huban assumes no responsibility for equipment failures that result from using products at values that exceed, even momentarily, rated values (such as maximum ratings, operating condition ranges, or other parameters) listed in products specifications of any and all Huban products described or contained herein.

3, Specifications of any and all Huban products described or contained here instipulate the performance, characteristics, functions of the described products in the independent state, and are not guarantees of the performance, characteristics, and functions of the described products as mounted in the customer's products or equipment. To verify symptoms and states that cannot be evaluated in an independent device, the customer should always evaluate and test devices mounted in the customer's products or equipment.

4, Huban Semiconductor CO., LTD. strives to supply high quality high reliabilityproducts. However, any and all semiconductor products fail with some probability. It is possible that these probabilistic failures could give rise to accidents or events that could endanger human lives that could give rise to smoke or fire, or that could cause damage to other property. Whendesigning equipment, adopt safety measures so that these kinds of accidents or events cannot occur. Such measures include but are not limited to protective circuits and error prevention circuits for safe design, redundant design, and structural design.

5, In the event that any or all Huban products (including technical data, services) described or contained herein are controlled under any of applicable local export control laws and regulations, such products must not be exported without obtaining the export license from the authorities concerned in accordance with the above law.

6, No part of this publication may be reproduced or transmitted in any form or by any means, electronic or mechanical, including photocopying and recording, or any information storage or retrieval system, or otherwise, without the prior written permission of Huban Semiconductor CO., LTD.

7, Information (including circuit diagrams and circuit parameters) herein is for example only; it is not guaranteed for volume production. Huban believes information herein is accurate and reliable, but no guarantees are made or implied regarding its use or any infringements of intellectual property rights or other rights of third parties.

8, Any and all information described or contained herein are subject to change without notice due to product/technology improvement, etc. When designing equipment, refer to the "DeliverySpecification" for the Huban product that you Intend to use.